Title (en)

INSTALLING AN ELECTRONIC ASSEMBLY

Title (de)

MONTAGE EINER ELEKTRONISCHEN BAUGRUPPE

Title (fr)

INSTALLATION D'ENSEMBLE ÉLECTRONIQUE

Publication

EP 3959745 A1 20220302 (DE)

Application

EP 20735078 A 20200615

Priority

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- EP 2020066453 W 20200615

Abstract (en)

[origin: WO2021018461A1] The invention relates to a method for installing an electronic assembly (10), having at least one die (40) and a substrate (150) with a conductive surface (152). The aim of the invention is to simplify the electric contacting of the dies during installation. This is achieved by the following step: arranging molded parts (21,..., 24), joining materials (30), and the at least one die (40) such that - the die (40) is electrically contacted by at least one of the molded parts (21,..., 24) and one of the joining materials (30) and - multiple functional elements (61, 62, 63) are formed from the molded parts (21,..., 24) and/or the die (40) and the joining materials (30), said functional elements being designed to support the substrate (150) and electrically contact the conductive surface (152). The invention additionally relates to an electronic assembly (10).

IPC 8 full level

H01L 21/60 (2006.01); **H01L 25/07** (2006.01)

CPC (source: CN EP US)

H01L 21/4853 (2013.01 - US); **H01L 21/6835** (2013.01 - US); **H01L 23/49811** (2013.01 - US); **H01L 23/49861** (2013.01 - US); **H01L 24/33** (2013.01 - CN EP); **H01L 24/40** (2013.01 - CN EP); **H01L 24/83** (2013.01 - CN EP US); **H01L 24/84** (2013.01 - CN EP); H01L 24/29 (2013.01 - CN EP); H01L 24/32 (2013.01 - CN EP US); H01L 24/33 (2013.01 - US); H01L 24/75 (2013.01 - CN EP); H01L 25/072 (2013.01 - CN EP); H01L 25/162 (2013.01 - CN EP); H01L 25/50 (2013.01 - CN EP); H01L 2221/68372 (2013.01 - US); H01L 2224/291 (2013.01 - CN EP); H01L 2224/30181 (2013.01 - CN EP); H01L 2224/32225 (2013.01 - US); H01L 2224/32227 (2013.01 - CN EP); H01L 2224/32245 (2013.01 - CN EP US); H01L 2224/33181 (2013.01 - CN EP US); H01L 2224/37147 (2013.01 - CN EP); H01L 2224/40229 (2013.01 - CN EP); H01L 2224/40491 (2013.01 - CN EP); H01L 2224/7598 (2013.01 - CN EP); H01L 2224/75983 (2013.01 - CN EP); H01L 2224/83 (2013.01 - CN); H01L 2224/83001 (2013.01 - CN EP); H01L 2224/83005 (2013.01 - US); H01L 2224/83191 (2013.01 - CN EP); H01L 2224/83801 (2013.01 - CN EP US); H01L 2224/8384 (2013.01 - CN EP US); H01L 2224/83906 (2013.01 - CN EP); H01L 2224/84 (2013.01 - CN); H01L 2224/84001 (2013.01 - CN EP); H01L 2224/84005 (2013.01 - CN EP); H01L 2224/97 (2013.01 - CN EP); H01L 2924/00014 (2013.01 - CN); H01L 2924/014 (2013.01 - CN); H01L 2924/13055 (2013.01 - CN EP US); H01L 2924/19105 (2013.01 - CN EP)

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See references of WO 2021018461A1

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